

Purging compound

TECHNICAL DATA SHEET



GL3 Grade

Asahi **KASEI**

Upgrade Version of Asaclean GL2 grade

Mechanical Purging Compound for Injection Molding & Extrusion

Packaging



GL3 Grade is available in : 20kg bags (pictured above)

PICTURED: Close-up of GL3 Grade

Product Safety

Refer to SDS for more information

Key Measurements

Specific Gravity	1.38~1.58
Softening Point	130℃



Issued: Oct 2023

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https://www.asahi-kasei.co.jp/asaclean/en/

Description & Benefits

- High-performance grade
 - * High cleaning power without glass fiber
- Suitable for general purpose use
 - * Ideal for most commodity and engineering resins
 - * Fast color/material change
 - * Remove carbon contamination
 - * Can be purged thorough hot runner
 - * Available for shutdown & sealing
- Mechanical purge (No chemical reaction)

Usage Information	
Temperature Range :	180℃ to 330℃
Applicant:	Injection Molding - including hot runners Extrusion - compounding, profile
Types of Resin:	Most commodity and engineering resins within the processing temperature range
Amount of Purge:	Typically 1-2 system capacities (actual amount depends on degree of contamination)
Minimum Clearance:	Requires 0.5 mm clearance for hot runner gates and extrusion dies; for extrusion screen packs, nothing finer than 100-mesh screen packs may be used.
Soak time:	Not required

* Detailed instruction may vary to optimize your purging process.

Physical & Chemical Properties	
Pellet color:	Light gray
Base resin:	Styrenic resin
Inorganic additives:	More than 40%
Stability:	Stable under normal temperatures
Reactivity:	Non-reactive under normal handling and storage conditions
Conditions to avoid:	Do not exceed recommended temperature range. Do not allow ASACLEAN GL3 Grade to reside in barrel for more than 30 minutes at temperatures higher than 280 ℃

Information in this document is subject to change without notice and it should be used for reference only.